

What is claimed is:

1. A test assembly for an integrated circuit package, the test assembly comprising:

a package substrate having a plurality of first contact pads linked in a first daisy chain pattern; and

5 a test board having a plurality of second contact pads linked in a second daisy chain pattern and a plurality of test pads, all of the second contact pads being divided into a plurality of groups each connected to one pair of test pads wherein all of the second contact pads in any group are arranged in a line,

10 wherein all of the second contact pads in any group are in a series electrical connection to one another through the first and second daisy chain patterns when the package substrate is mounted on the test board, and all of the second contact pads in any group form a closed circuit when the corresponding pair of test pads are probed.

15 2. The test assembly as claimed in claim 1, wherein the test board comprises a pair of major test pads such that all of the second contact pads form a closed circuit when the pair of major test pads is probed.

3. The test assembly as claimed in claim 1, wherein the package substrate is a ball grid array substrate.

4. A method of testing an integrated circuit package having a substrate with a plurality of first contact pads linked in a first daisy chain pattern, the method comprising:

20 providing a test board having a plurality of second contact pads linked in a second daisy chain pattern and a plurality of test pads, all of the second contact pads being divided into a plurality of groups each connected to one pair of test pads wherein all of the second contact pads in any group are arranged in a line;

25 mounting the integrated circuit package on the test board by reflowing solder bumps provided on the integrated circuit package to the second contact pads of the test board wherein all of the second contact pads in any group are in a series electrical connection to one another through the first and second daisy chain patterns; and

performing an electrical test after conducting the mounting step,

30 wherein all of the second contact pads in any group form a closed circuit when the corresponding pair of test pads are probed.

5. The method as claimed in claim 4, wherein the test board comprises a pair of major test pads such that all of the second contact pads form a closed circuit when the pair of major test pads is probed.